KBJ10005 THRU KBJ1010

GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER



REVERSE VOLTAGE: 50 to 1000 VOLTS FORWARD CURRENT: 10.0 AMPERE

FEATURES

· Glass passivated chip junction

· Reliable low cost construction utilizing molded plastic technique

· Ideal for printed circuit board

· Low forward voltage drop

· Low reverse leakage current

· High surge current capability

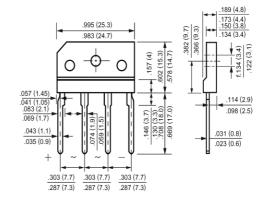
MECHANICAL DATA

Case: Molded plastic, GBJ

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,

method 208 guaranteed Mounting position: Any Weight: 0.23ounce, 6.6gram KBJ



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified.

Single phase, half wave, $60H_Z$, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	KBJ10005	KBJ1001	KBJ1002	KBJ1004	KBJ1006	KBJ1008	KBJ1010	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current with Heatsink at T_C =110	I _(AV)	10.0							Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I _{FSM}	170							Amp
Maximum Forward Voltage Drop per Element at 5.0A DC and 25	V_{F}	1.05							Volts
Maximum Reverse Current at T_A =25 at Rated DC Blocking Voltage T_A =125	I_R	5.0 500							uAmp
Typical Junction Capacitance (Note 1)	C_{J}	55							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	1.4							/W
Operating and Storage Temperature Range	T _J , Tstg	-55 to +150							

NOTES:

- 1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.
- 2- Thermal Resistance from Junction to Case with Device Mounted on 150mm x 1.6mmCu Plate Heatsink.



RATINGS AND CHARACTERISTIC CURVES

